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XP-002229219

AN - 1987-275700 [39]
 A - [001] 014 02& 04- 040 07- 075 080 09& 140 15- 18& 180 213 214 215 226
 231 308 311 316 332 335 341 398 44& 473 506 509 532 536 623 627 628
 654 681
 AP - SU19823473518 19820723
 CPY - CHIM-I
 - KHIM-I
 - RADK-I
 DC - A21 A85 E17 L03 X12
 DR - 0272-U 0954-U 0954-U
 FS - CPI;EPI
 IC - H01B1/22
 IN - DEGTYAREVA L N; KHIMCHENKO Y U I; RADKEVICH L S
 KS - 0035 0036 0037 0105 0123 0218 0224 0226 0231 1277 1282 1357 1517 2020
 2220 2299 2318 2507 2551 2572 2574 2737 2740
 MC - A05-A01B1 A05-C03 A08-D A08-M09A A09-A03 A12-E01 E10-C04H L03-A01A3
 L03-H04E4
 - X12-D01X
 M3 - [01] H7 H721 J0 J011 J1 J171 M225 M231 M262 M281 M320 M416 M781 M903
 M904 M910 Q130 Q454 R043; R00954-U; 8714-0 1286-M
 PA - (CHIM-I) CHIMCENKO J I
 - (KHIM-I) KHIMCHENKO Y U I
 - (RADK-I) RADKEVIC L S
 PN - SU1098441 A 19870307 DW198739 006pp
 - CS8408887 A 19871015 DW198746 000pp
 - DD258733 A 19880803 DW198848 000pp
 PR - SU19823473518 19820723
 XA - C1987-117312
 XIC - H01B-001/22
 XP - N1987-206486
 AB - SU1098441 The compsn. contains (wt.%): epoxy resin 2.7-15;
 phenolformaldehyde resin (as curing agent) 3-15; dendrite highly
 dispersed iron 0.4-59.5; spherical highly dispd. nickel 0.3-75; oleic
 acid 0.008-0.242; solvent to 100. The pref. solvent compsn. contains
 (wt.%): ethyl cellosolve 30-40; butanol 25-30; acetone 25-30; xylol -
 5-10, or (wt.%): ethyl cellosolve 45-55; benzyl alcuhol 35-40; xylol
 10-15, or (wt.%): ethyl cellosolve 20-40; benzyl alcohol 60-80. As
 previously, the compsn. contains epoxy resin, curing agent and highly
 dispd. metal.
 - USE/ADVANTAGE - Increased storage life of compsn. (by 6 fold), reduced
 cost (by 20-50 fold) while maintaining high electroconductivity,
 simpler technology of use, and improved working conditions. The
 compsn. may be used to mfr. printed circuits, electrical connections
 etc.
 - In an example, the compsn. contg. (wt.%): epoxy resin 4; phenol
 formaldehyde resin 4; Ni 74.6; Fe 0.4 oleic acid 0.008; ethyl
 cellosolve 17, gave vol. resistivity (ohm cm): 0.007 after 1 days
 storage; 0.008 after 6 months. Bul.9/7.3.87 (6pp Dwg.No 0/0)

CN - R00954-U

DRL - 8714-0 1286-M

I/W - E1 ELECTROCONDUCTING COMPOSITION CONTAIN POLYEPOXIDE RESIN CONTAIN

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SPECIFIED CURE AGENT HIGH DISPERSE METAL SUPPLEMENTARY OLEIC ACID
SOLVENT

IKW - ELECTROCONDUCTING COMPOSITION CONTAIN POLYEPOXIDE RESIN CONTAIN
SPECIFIED CURE AGENT HIGH DISPERSE METAL SUPPLEMENTARY OLEIC ACID
SOLVENT

INW - DEGTYAREVA L N; KHIMCHENKO Y U I; RADKEVICH L S

NC - 003

OPD - 1982-07-23

ORD - 1987-03-07

PAW - (CHIM-I) CHIMCENKO J I

- (KHIM-I) KHIMCHENKO YU I

- (RADK-I) RADKEVIC L S

TI - Electroconductive compsn. contg. epoxy] resin - contains specified
curing agent highly dispersed metal and supplementary oleic acid and
solvent